

ABSOLUTE MAXIMUM RATINGS									
PARAMETER	SYMBOL	TEST CONDITIONS			VALUES				
PARAMETER	STMBOL TEST CONDITIONS		TYP.	UNITS					
Maximum average on-state current	I _{T(AV)}	T _C = 93 °C, 180° co	onduction half sine wave	1	A				
Maximum RMS on-state current	I _{RMS}			25					
Maximum peak, one-cycle,	I	10 ms sine pulse, r	ated V _{RRM} applied	3	00	Α			
non-repetitive surge current	I _{TSM}	10 ms sine pulse, r	no voltage reapplied	3	50				
Maximum I ² t for fusing	I ² t	10 ms sine pulse, rated V _{RRM} applied			50	A ² s			
Wiaximum i-t for fusing	I-I	10 ms sine pulse, no voltage reapplied			30				
Maximum I ² √t for fusing	I ² √t	t = 0.1 ms to 10 ms	6300		A²√s				
Maximum on-state voltage drop	V_{TM}	16 A, T _J = 25 °C	1.25		V				
On-state slope resistance	r _t	T _{.1} = 125 °C		12.0		mΩ			
Threshold voltage	V _{T(TO)}	1) = 125 C		1.0		V			
Maximum reverse and direct leakage current		T _J = 25 °C	V = rotad V = A/	0	.5				
Maximum reverse and direct leakage current	I _{RM} /I _{DM}	T _J = 125 °C	$V_R = \text{rated } V_{RRM} / V_{DRM}$ 10		0				
Holding current	I _H	Anode supply = 6 V, resistive load, initial I_T = 1 A, T_J = 25 °C			150	mA			
Maximum latching current	ΙL	Anode supply = 6 V, resistive load, T _J = 25 °C			00				
Maximum rate of rise of off-state voltage	dV/dt	$T_J = T_J \text{ max., linear to } 80 \%, V_{DRM} = R_g - k = open$			00	V/µs			
Maximum rate of rise of turned-on current	dl/dt				150				

TRIGGERING				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum peak gate power	P _{GM}		8.0	W
Maximum average gate power	P _{G(AV)}		2.0	VV
Maximum peak positive gate current	+ I _{GM}		1.5	Α
Maximum peak negative gate voltage	- V _{GM}		10	V
Maximum required DC gate current to trigger		Anode supply = 6 V, resistive load, T _J = - 10 °C	60	
	I _{GT}	Anode supply = 6 V, resistive load, T _J = 25 °C	45 mA	
		Anode supply = 6 V, resistive load, T _J = 125 °C	20	ļ
		Anode supply = 6 V, resistive load, T _J = - 10 °C	2.5	
Maximum required DC gate voltage to trigger	V_{GT}	Anode supply = 6 V, resistive load, T _J = 25 °C	2.0	v
		Anode supply = 6 V, resistive load, T _J = 125 °C	1.0	V
Maximum DC gate voltage not to trigger	V_{GD}	T 105 °C V Detect value	0.25	
Maximum DC gate current not to trigger	I _{GD}	T _J = 125 °C, V _{DRM} = Rated value	2.0	mA

SWITCHING									
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS					
Typical turn-on time	t _{gt}	T _J = 25 °C	0.9						
Typical reverse recovery time	t _{rr}	T _{.1} = 125 °C	4	μs					
Typical turn-off time	t _q	1j = 125 C	110						



THERMAL AND MECHANICAL SPECIFICATIONS									
PARAMETER SYMBOL TEST CONDITIONS VALUES UN									
Maximum junction and storage temperature range	T _J , T _{Stg}		-40 to +125	°C					
Soldering temperature	Ts	For 10 s (1.6 mm from case)	260						
Maximum thermal resistance, junction to case	R _{thJC}	DC operation	1.1	°C/W					
Typical thermal resistance, junction to ambient (PCB mount)	R _{thJA} ⁽¹⁾		40	C/VV					
Approximate weight			2	g					
Approximate weight			0.07	OZ.					
Marking device		Case style D ² PAK (TO-263AB)	25TT	S16S					

Note

⁽¹⁾ When mounted on 1" square (650 mm²) PCB of FR-4 or G-10 material 4 oz. (140 µm] copper 40 °C/W; for recommended footprint and soldering techniques refer to application note #AN-994

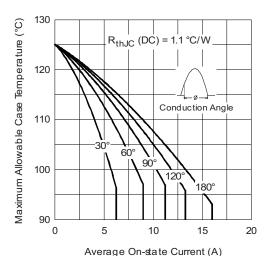


Fig. 1 - Current Rating Characteristics

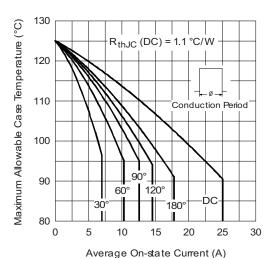


Fig. 2 - Current Rating Characteristics

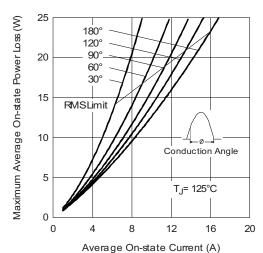


Fig. 3 - On-State Power Loss Characteristics

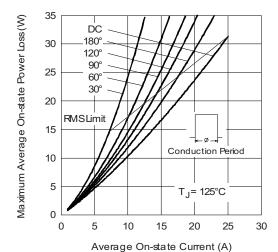


Fig. 4 - On-State Power Loss Characteristics



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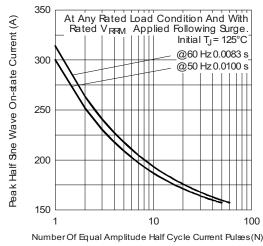


Fig. 5 - Maximum Non-Repetitive Surge Current

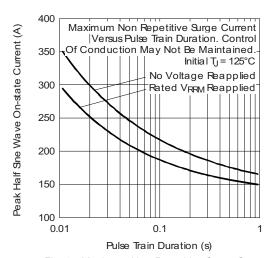


Fig. 6 - Maximum Non-Repetitive Surge Current

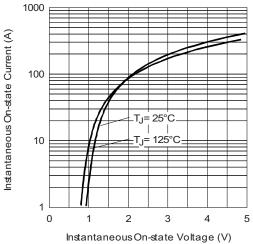
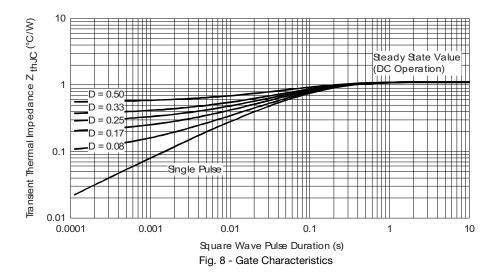


Fig. 7 - On-State Voltage Drop Characteristics



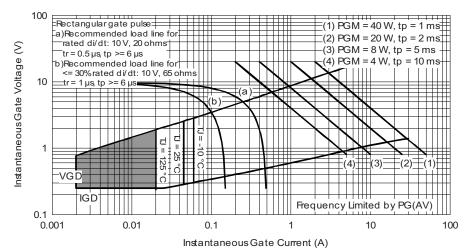


Fig. 9 - Thermal Impedance Z_{thJC} Characteristics

ORDERING INFORMATION TABLE

Danisha		0.5		_		40				
Device code	VS-	25	Т	T	S	16	S	TRL	PbF	
	1	2	3	4	5	6	7	8	9	
	1 .	Visl	nay Sen	niconduc	ctors pro	oduct				
	2 -	Cur	rent rati	ng (25 =	= 25 A)					
	3 -		Circuit configuration:							
	4	Pac	single t kage: TO-220							
	5	٠.	e of silic		am, raat	ifiar				
	6			rd recoving: volta	•		= V _{RRN}	1	16 = 1	
	7	S =	TO-220	D ² PAK	(TO-26	3AB) v	ersion			
	8 -	• TF	•	be e and re be and re	`		,			
	9 -	PbF	= lead	(Pb)-fre	е					

ORDERING INFORMATION (Example)									
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION						
VS-25TTS16SPbF	50	1000	Antistatic plastic tubes						
VS-25TTS16STRRPbF	800	800	13" diameter reel						
VS-25TTS16STRLPbF	800	800	13" diameter reel						

LINKS TO RELATED DOCUMENTS						
Dimensions	www.vishay.com/doc?95046					
Part marking information	www.vishay.com/doc?95054					
Packaging information	www.vishay.com/doc?95032					

Revision: 10-Aug-2018 5 Document Number: 94679



D²PAK

DIMENSIONS in millimeters and inches



SYMBOL	MILLIM	ETERS	INC	HES	NOTES	SYMBOL	MILLIMETERS		INCHES		NOTES	
STIVIBUL	MIN.	MAX.	MIN.	MAX.	NOIES	NOTES	STWIDOL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.06	4.83	0.160	0.190			D1	6.86	8.00	0.270	0.315	3
A1	0.00	0.254	0.000	0.010			Е	9.65	10.67	0.380	0.420	2, 3
b	0.51	0.99	0.020	0.039			E1	7.90	8.80	0.311	0.346	3
b1	0.51	0.89	0.020	0.035	4		е	2.54 BSC		0.100 BSC		
b2	1.14	1.78	0.045	0.070			Н	14.61	15.88	0.575	0.625	
b3	1.14	1.73	0.045	0.068	4		L	1.78	2.79	0.070	0.110	
С	0.38	0.74	0.015	0.029			L1	-	1.65	-	0.066	3
c1	0.38	0.58	0.015	0.023	4		L2	1.27	1.78	0.050	0.070	
c2	1.14	1.65	0.045	0.065			L3	0.25	BSC	0.010	BSC	
D	8.51	9.65	0.335	0.380	2		L4	4.78	5.28	0.188	0.208	

Notes

- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inch
- (7) Outline conforms to JEDEC® outline TO-263AB

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